

HOSTAFORM® LW90BSX

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Hostaform® LW90BSX is a specialty low wear grade of acetal copolymer designed for a wide range of tribological applications, including POM/POM pairings. This grade's low wear system includes silicone oil.

Product information

Resin Identification	POM	ISO 1043
Part Marking Code	>POM<	ISO 11469

Rheological properties

Melt volume-flow rate	7 cm ³ /10min	ISO 1133
Temperature	190 °C	
Load	2.16 kg	

Typical mechanical properties

Tensile modulus	2350 MPa	ISO 527-1/-2
Tensile stress at yield, 50mm/min	51 MPa	ISO 527-1/-2
Tensile strain at yield, 50mm/min	15 %	ISO 527-1/-2
Nominal strain at break	35 %	ISO 527-1/-2
Flexural modulus	2250 MPa	ISO 178
Charpy impact strength, 23°C	85 kJ/m ²	ISO 179/1eU
Charpy impact strength, -30°C	75 kJ/m ²	ISO 179/1eU
Charpy notched impact strength, 23°C	5.5 kJ/m ²	ISO 179/1eA
Ball indentation hardness, H 358/30	120 MPa	ISO 2039-1
Poisson's ratio	0.38 ^[C]	

[C]: Calculated

Thermal properties

Melting temperature, 10°C/min	166 °C	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	90 °C	ISO 75-1/-2

Physical/Other properties

Density	1370 kg/m ³	ISO 1183
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Injection

Drying Recommended	no
Drying Temperature	100 °C
Drying Time, Dehumidified Dryer	3 - 4 h
Processing Moisture Content	≤0.2 %
Melt Temperature Optimum	200 °C
Min. melt temperature	190 °C
Max. melt temperature	210 °C
Screw tangential speed	≤0.3 m/s
Mold Temperature Optimum	100 °C
Min. mould temperature	80 °C
Max. mould temperature	120 °C
Hold pressure range	60 - 120 MPa
Back pressure	4 MPa

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Characteristics

Processing	Injection Moulding
Delivery form	Pellets
Additives	Release agent
Special characteristics	Low wear / Low friction

Additional information

Processing Notes

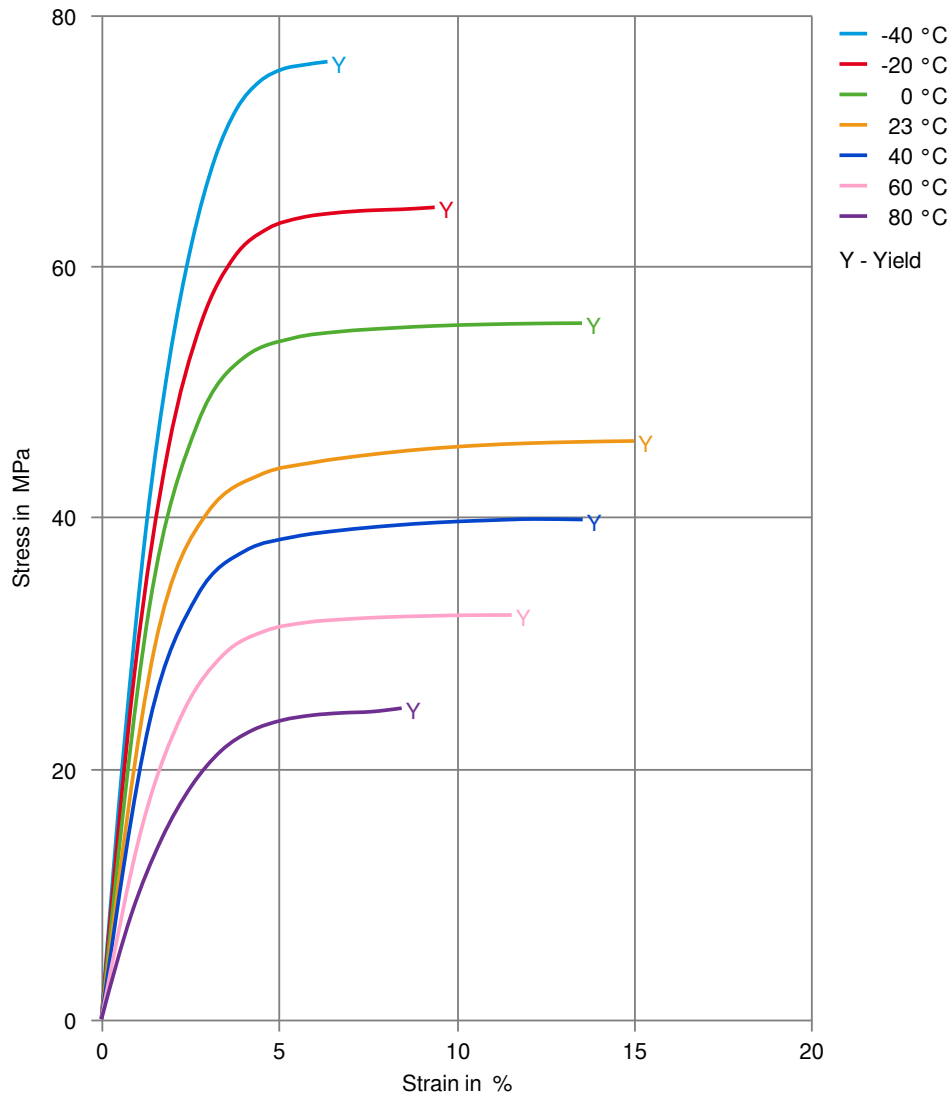
Storage

The product can then be stored in standard conditions until processed.

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Stress-strain



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Secant modulus-strain

